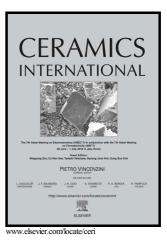
## Author's Accepted Manuscript

Film thickness effect on texture and residual stress sign transition in sputtered TiN thin films

Yeting Xi, Kewei Gao, Xiaolu Pang, Huisheng Yang, Xiaotao Xiong, Hong Li, Alex A. Volinsky



 PII:
 S0272-8842(17)31252-X

 DOI:
 http://dx.doi.org/10.1016/j.ceramint.2017.06.050

 Reference:
 CERI15572

To appear in: Ceramics International

Received date: 24 April 2017 Revised date: 1 June 2017 Accepted date: 7 June 2017

Cite this article as: Yeting Xi, Kewei Gao, Xiaolu Pang, Huisheng Yang, Xiaotao Xiong, Hong Li and Alex A. Volinsky, Film thickness effect on texture and residual stress sign transition in sputtered TiN thin films, *Ceramic International*, http://dx.doi.org/10.1016/j.ceramint.2017.06.050

This is a PDF file of an unedited manuscript that has been accepted fo publication. As a service to our customers we are providing this early version o the manuscript. The manuscript will undergo copyediting, typesetting, and review of the resulting galley proof before it is published in its final citable form. Please note that during the production process errors may be discovered which could affect the content, and all legal disclaimers that apply to the journal pertain

### ACCEPTED MANUSCRIPT

#### Film thickness effect on texture and residual stress sign transition in

#### sputtered TiN thin films

Yeting Xi<sup>a</sup>, Kewei Gao<sup>a</sup>, Xiaolu Pang<sup>a\*</sup>, Huisheng Yang<sup>a</sup>, Xiaotao Xiong<sup>b</sup>, Hong

Li<sup>b</sup>, Alex A. Volinsky <sup>c\*</sup>

<sup>a</sup> School of Materials Science and Engineering, University of Science and Technology Beijing, Beijing 100083, P.R. China

<sup>b</sup> Institute for Advanced Materials and Technology, University of Science and Technology Beijing, Beijing 100083, P.R. China

<sup>c</sup> Department of Mechanical Engineering, University of South Florida, Tampa, FL 33620, USA

pangxl@mater.ustb.edu.cn

volinsky@usf.edu

Corresponding authors.

#### Abstract

Residual stress in thin films and coatings strongly affects their properties and behavior in service. Comprehensive understanding and precise measurements of residual stress are prerequisites for preparing high quality films and coatings. Residual stresses in TiN films with different thickness were measured by X-ray diffraction (XRD) employing the  $\cos^2 \alpha \sin^2 \psi$  method with certain optimization. Grazing incidence parallel beam optics was combined with side-inclination geometry using in-house designed sample stage to ensure results accuracy. To validate this method, TiN films with the thickness ranging from 1 to 3 µm were deposited on (100) Si single crystal substrates at 300 °C by RF Download English Version:

# https://daneshyari.com/en/article/5437490

Download Persian Version:

https://daneshyari.com/article/5437490

Daneshyari.com